Features :

- Isolated mounting base 3000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

V_{DSM},V_{RSM}	V_{DRM},V_{RRM}	Type
2100V	2000V	Mx250TH200
2300V	2200V	Mx250TH220
2600V	2500V	Mx250TH250

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(℃)	VALUE			UNIT
				Min	Type	Max	
$I_{T(AV)}$	Mean on-state current	180° half sine wave 50Hz Single side cooled, T_c=85℃	125			250	A
$I_{T(RMS)}$	RMS on-state current					393	A
I_{DRM} I_{RRM}	Repetitive peak current	at V_{DRM} at V_{RRM}	125			30	mA
I_{TSM}	Surge on-state current	10ms half sine wave V_R=60%V_{RRM}	125			9.0	kA
I^2t	I^2t for fusing coordination					405	A^2S*10^3
V_{TO}	Threshold voltage		125			0.85	V
r_T	On-state slope resistance					0.80	mΩ
V_{TM}	Peak on-state voltage	I_{TM}=750A	25			1.73	V
dv/dt	Critical rate of rise of off-state voltage	V_{DM}=67%V_{DRM}	125			1000	V/μs
di/dt	Critical rate of rise of on-state current	Gate source 1.5A t_r ≤0.5μs Repetitive	125			200	A/μs
I_{GT}	Gate trigger current	V_A=12V, I_A=1A	25	30		180	mA
V_{GT}	Gate trigger voltage			0.8		2.5	V
I_H	Holding current			20		150	mA
V_{GD}	Non-trigger gate voltage	V_{DM}=67%V_{DRM}	125	0.2			V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled per chip				0.12	℃/W
$R_{th(c-h)}$	Thermal resistance case to heat sink	Single side cooled per chip				0.04	℃/W
V_{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I_{iso}:1mA(MAX)		3000			V
F_m	Terminal connection torque (M8)				12.0		N·m
	Mounting torque (M6)				6.0		N·m
T_{vj}	Junction temperature			-40		125	℃
T_{stg}	Stored temperature			-40		125	℃
W_t	Weight				810		g
Outline	M03						

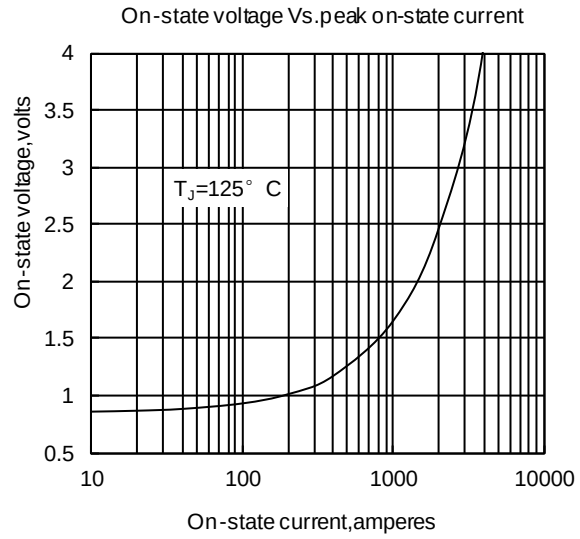

Fig. 1

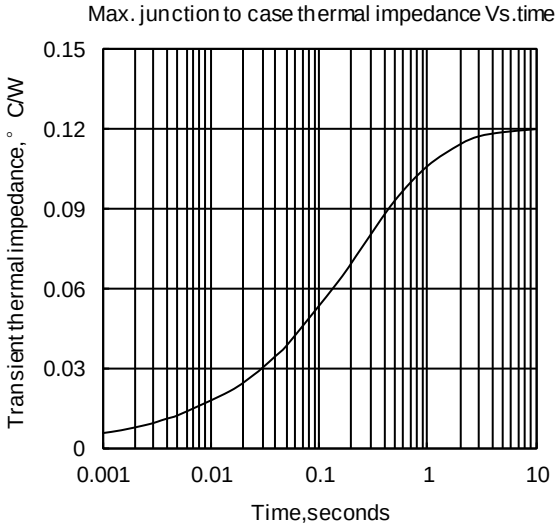

Fig. 2

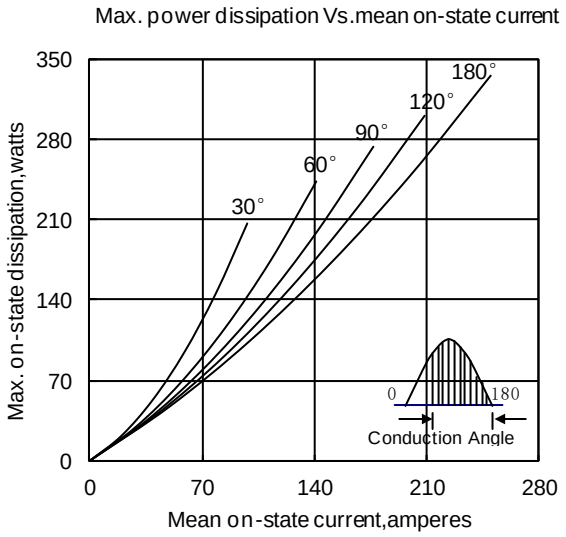

Fig. 3

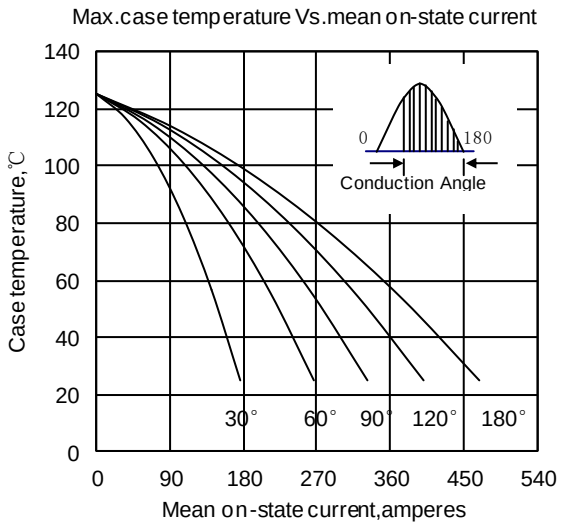

Fig. 4

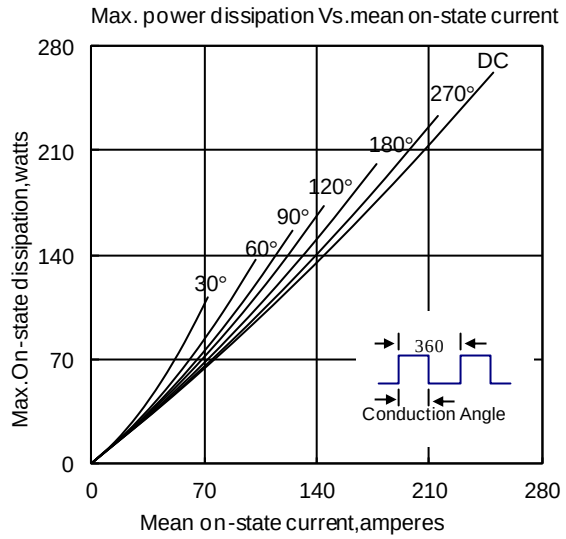

Fig. 5

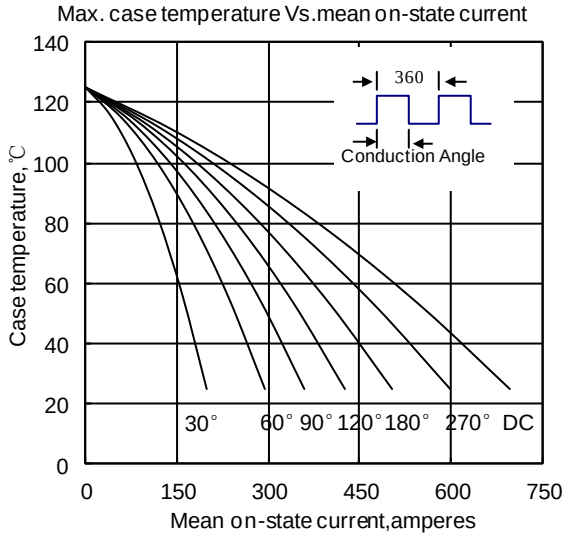

Fig. 6

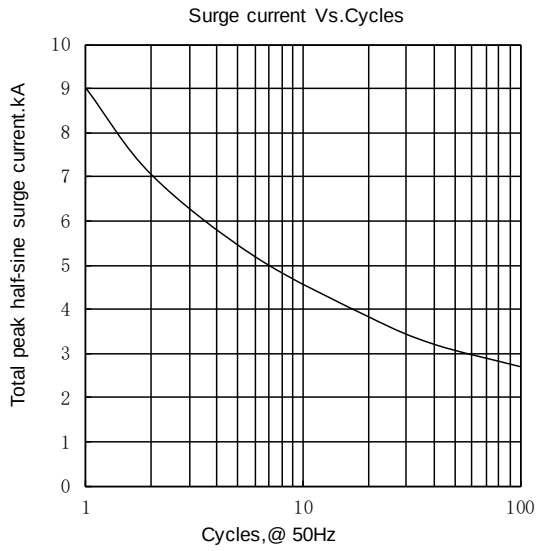

Fig.7

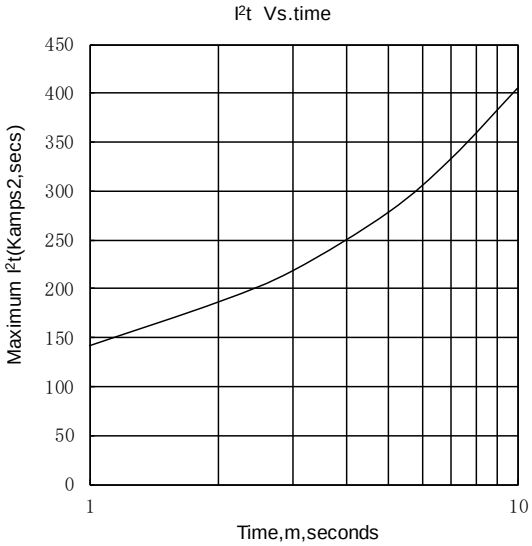

Fig.8

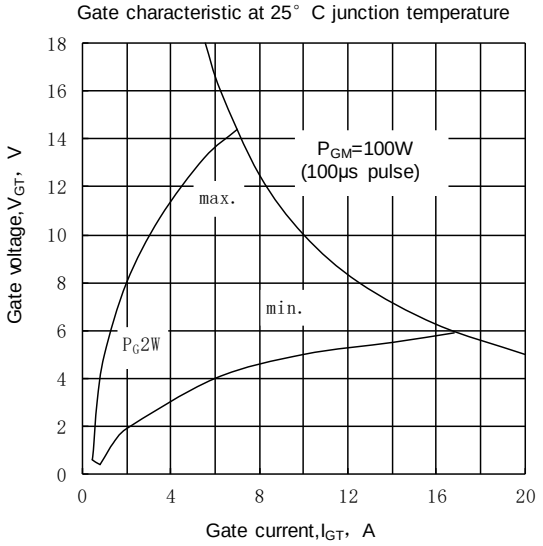

Fig.9

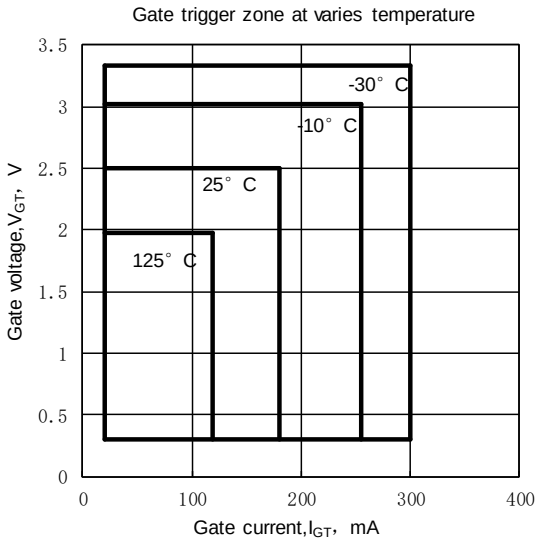

Fig.10

Outline: